

## REMARKS

In accordance with the foregoing, claims 1, 2, 12, 13, 14, 17 and 18 have been amended. Claim 21 is cancelled herein. Claims 1-21 are pending and under consideration. Claims 3, 5, 7, 9, 16 and 20 are allowed. Claims 2, 4, 6, 8, 12, 14 and 18 are objected to.

### DRAWING OBJECTION

The Examiner's attention is drawn to the present specification (see, e.g., line 4-5, page 14 and from lines 8-9, page 28). Specifically, these portions refer to spacer 10a being formed of a spacer body 1a having a frame like shape with no ends thereof. Accordingly, withdrawal of the rejection is requested.

### CLAIM OBJECTION/SPECIFICATION OBJECTION

These objections are moot due to the cancellation of claim 21.

### REJECTION UNDER 35 U.S.C. § 103

Claims 1, 10-11, 13, 15, 17, 19, and 21 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Tsuchiyama (U.S. Patent No. 7,119,430) in view of Turturro (U.S. Patent No. 6,088,915).

Independent claim 1 (used as an example herein) recites "the elastic member being attached to and detached from the printed wiring board on which the electronic component is fixed, by exploiting elastic deformation of the elastic member."

In contrast, Tsuchiyama discloses spacer 3 between circuit board 1 and mounting members 23 of chip packages 21, but does not disclose that the spacer 3 is attached to and detached from the circuit board 1 on which the mounting members 23 are fixed, by exploiting elastic deformation of the spacer 3 (refer to FIGS. 4A-4B and FIGS 7-10 of Tsuchiyama).

Also, Turturro discloses spacer 44 is interposed between integrated circuit 16 and heat conductive member 42, but does not disclose that the spacer 44 is attached to and detached from the integrated circuit 16 on which the heat conductive member 42 is fixed, by exploiting elastic deformation of the spacer 44 (refer to FIG. 2 of Turturro).

The claimed invention is advantageous as compared to the cited references, because when soldering an electronic component onto the printed wiring method, and also when removing the electronics component from the printed wiring board, the present spacer does not need to be manufactured from a material which is resistant to heat caused by soldering, thereby reducing the manufacturing cost of the spacer (see, e.g. from line 19 on page 9 through line 3 on

page 10 of the present Specification).

Accordingly, withdrawal of the rejection is requested.

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

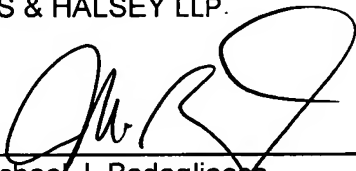
Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP.

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